
HYBRID AND MODULE QC R0-FOCUSED

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QUALITY CONTROL VS ASSURANCE

- QA: process oriented (sound design, cleanrooms, instructions, standards) - not this talk
- QC: product oriented (testing product quality)
- Oxford English dictionary:
- Control: *the restriction of an activity, tendency, or phenomenon.*
- E.g. 'crime control'



X



OVERVIEW (TDR)

- 7.6.1 Silicon Sensor (covered in Sensor session)
- 7.6.2 Hybrid Production Control
- 7.6.3 Hybrid & Module Visual Inspection
- 7.6.4 Hybrid & Module Metrology
- 7.6.5 Hybrid & Module Wire-bonding QC
- 7.6.6 Pass/Fail Grading for Wire-Bonded Hybrids & Modules
- 7.6.7 Hybrid & Module Electrical Tests

MAIN AIMS OF R0 QC

- Test the parameters of the assembled modules thus qualifying our design, production methods and QA
- Compare the results at various sites
- Test the proposed test sets thus qualifying our QC ideas
- Bring info for module parameter definition
- Test the existing test setups at institutions
- Test the data management (production database)

HYBRID PRODUCTION CONTROL

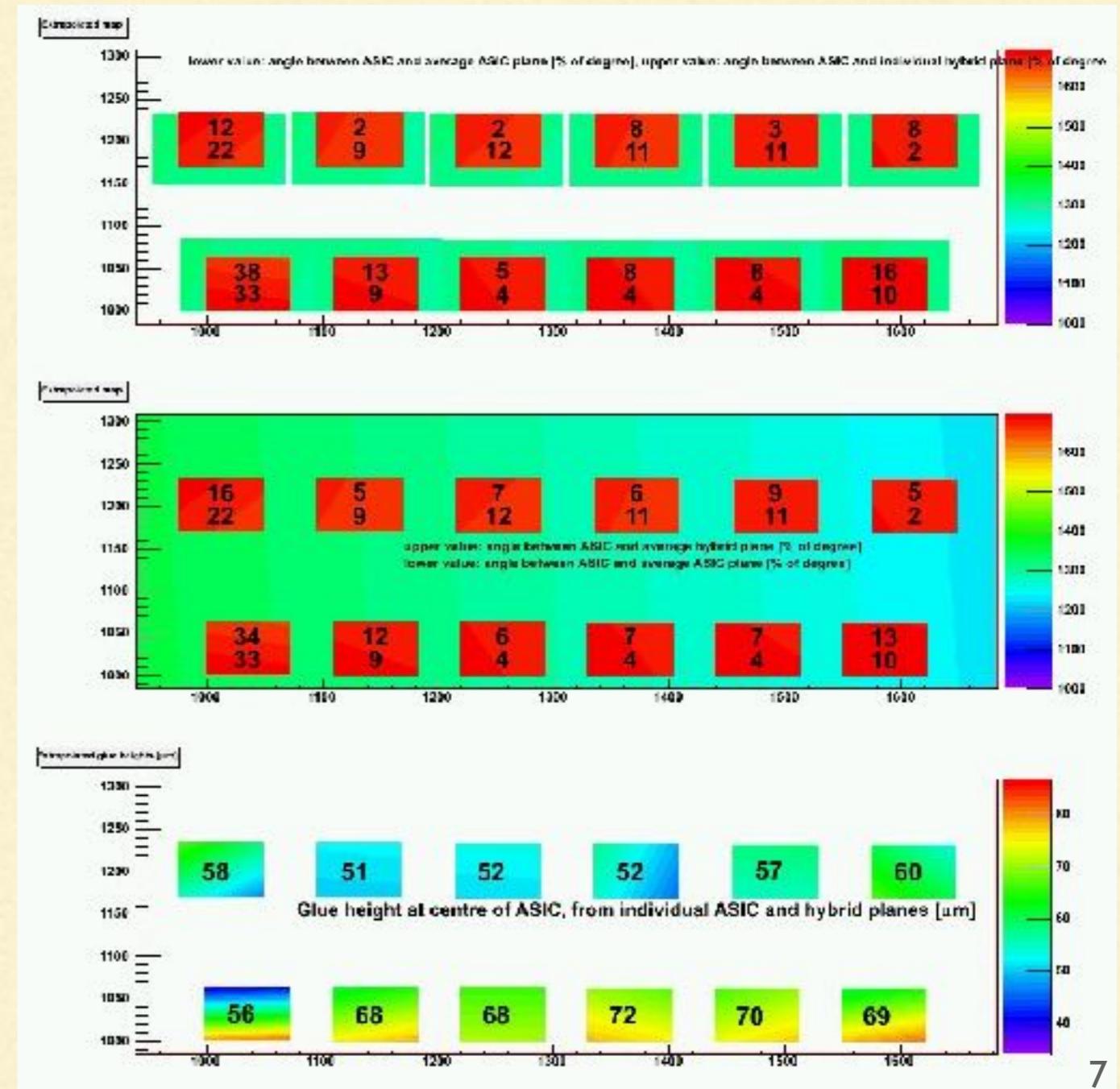
- Flex QC (Vendor)
- Passive component QC (Vendor)
- Basic electrical test after wire bonding (Institutes, PDB) Y
- Burn-in (Institutes) N
- To identify ASIC infant mortality: not really task for R0 - skip

HYBRID AND MODULE VISUAL INSPECTION

- Tests/things to check:
 - Missing or damaged SMD components
 - Glue seepage covering wire bond pads or sensor guard rings
 - Debris or physical contaminants on items
 - Missing or dangling wire-bonds
- After each bonding row
- Photos uploaded to PDB

HYBRID AND MODULE METROLOGY (I, PDB)

- Tests:
 - x-y Hybrid Constraints
 - z Hybrid Constraints
 - Module Constraints in x-y
 - Module Constraints in z
- Do we have sets of measurement points?



HYBRID ELECTRICAL TESTS (I, PDB)

- Tests:
 - Chip Communication
 - Strobe delay
 - Three Point gain
 - Noise Occupancy
- Gained experience from Travelling DAQload
- Standard macros needed

MODULE ELECTRICAL TESTS (I, PDB)

- Tests:
 - Chip Communication
 - Strobe delay
 - Tuning (Trimming)
 - Response curve
 - Noise Occupancy
 - I-V curve
- Gained experience from Travelling DAQload
- Standard macros needed

THERMAL CYCLING AND LOW TEMPERATURE TESTING

- Thermal cycling considered necessary
- Temperature ranges to be defined (see next slide)
- Speeds TBD
- # of cycles: hybrid: 10, module:TBD
- Arrangement options:
 - jigs (+chillers or environmental chamber)
 - environmental chamber (w or w/o vacuum?)
 - modules biased/powered?

THERMAL CYCLING AND LOW TEMPERATURE TESTING

A.Blue, April 2015

| Temperature °C | SCT Barrel Module | ECT E/C Module | Upgrade Barrel Module | Upgrade E/C Module |
|-------------------------|------------------------------------|------------------------|----------------------------|--------------------|
| Hybrids | | | | |
| Characterisation | 27°C 37°C 0°C | 0°C +/- 5°C | ?? | Same |
| LTT (first 50) | 90 hrs at 37 °C 10 hr at 0 °C | 90 hrs at 55°C 500V | -35 | Same |
| LTT (after 50) | >10 hr at 37 °C > 10 hr at 0 °C | -- | -35 | Same |
| Thermal Cycling | -- | -30°C to +50°C x10 | -35 | Same |
| Modules | | | | |
| Long Term Tests | +0°C >20hrs | 10°C >24hrs | -35 V hard to do | Same |
| Thermal Cycling | -25°C to +40°C x10 | -30°C to +30°C x10 | -35 | Same |
| Thermal Shock | -- | -- | -35 | Same |

TDR:
-40 degC

DATA MANAGEMENT

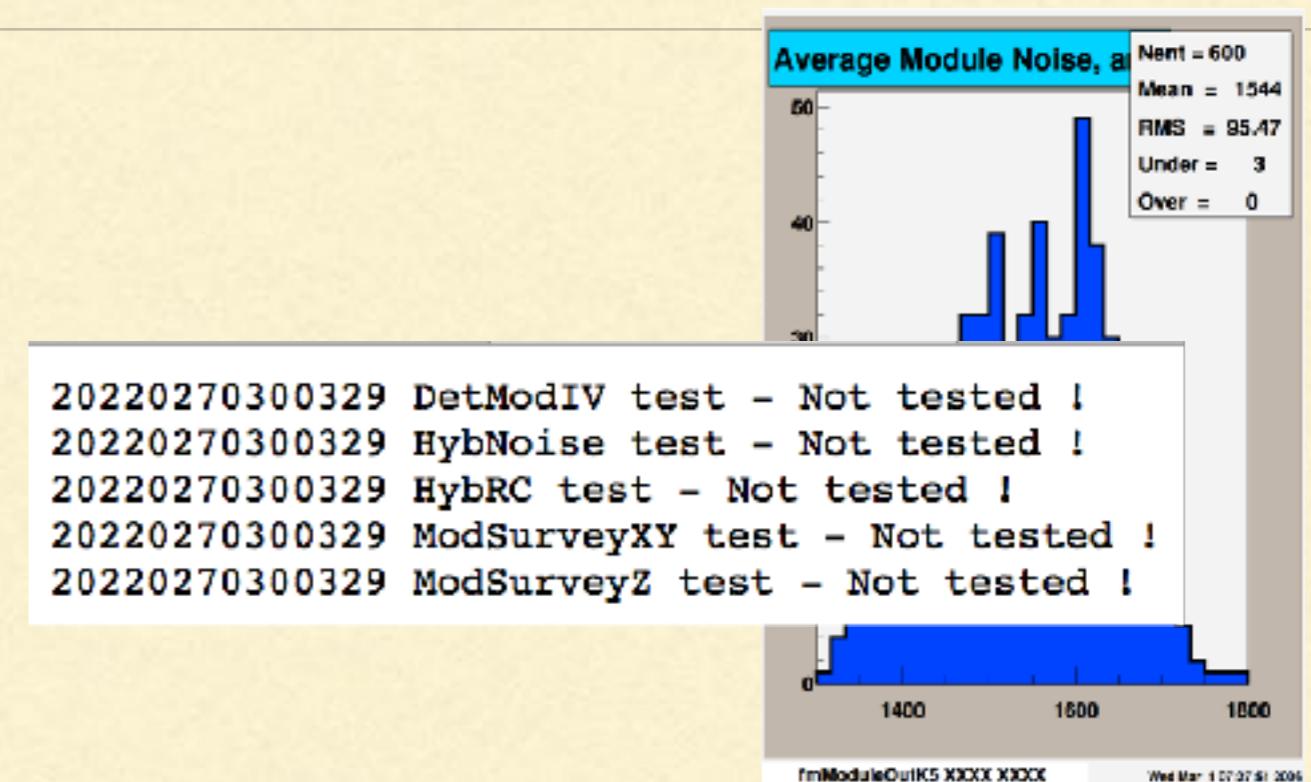
- Production database under development
- Andy communicates strip requirements
- Tools for module test uploads hopefully ready for R0 campaign
- Reporting not necessarily mature enough to get what we want
- Parallel spreadsheets necessary (a la DAQload)

PRODUCTION PROSPECTS

- R0 campaign should provide essential info on the production QC:
- necessity of steps
- number of cycles, tests needed
- feasibility of steps w.r.t. duration

SCT PRODUCTION TRACKING (ZD)

| Topic | Plots |
|---------------------------------|---|
| List of serial numbers | List of serial numbers |
| Missing tests | Missing tests |
| Average and chip gain | Average gain, Chip gain |
| Average and chip noise | Average noise, Chip noise |
| Average and chip NO | Average NO, Chip NO |
| Leakage current | Current @150 and @ 350V |
| Masked channels (from RC tests) | Number of masked channels |
| Hybrid temperature | Hybrid temperature |
| XY and Z Metrology | XY, Z |



Module types

| Y/M | Inner | L/Mid | S/Mid | Out | Total |
|--------|--------------|-------|-------|---------------|----------------|
| 200302 | - | - | - | 3 0 0 | 3 0 0 |
| 200303 | 2 2 0 | - | - | 10 9 2 | 12 11 2 |

Statistics of production sites

| Y/M | Nikhef | Fr | Val | Man | Gva | MPI | Melb | Total |
|--------|--------------|----|--------------|--------------|--------------|--------------|------|----------------|
| 200302 | - | - | 3 0 0 | - | - | - | - | 3 0 0 |
| 200303 | 2 2 0 | - | 1 0 0 | 2 2 2 | 7 7 0 | - | - | 12 11 2 |
| 200305 | - | - | - | 3 3 3 | 1 1 1 | 1 0 0 | - | 5 4 4 |

PRODUCTION TRACKING (CL)

| Summary | Built | Good | Pass | Hold | Failed | Not tested | Yield (G) | Yield (G+P) | Done⁽¹⁾ | Needed | Remaining⁽²⁾ |
|-----------------|--------------|-------------|-------------|-------------|---------------|-------------------|------------------|--------------------|---------------------------|---------------|--------------------------------|
| All | 2389 | 2052 | 158 | 113 | 55 | 11 | 86.3% | 92.9% | 107.9% | -172. | -48. |
| Clusters | Built | Good | Pass | Hold | Failed | Not tested | Yield (G) | Yield (G+P) | Done⁽¹⁾ | Needed | Remaining⁽²⁾ |
| UK-V | 916 | 798 | 60 | 46 | 12 | 0 | 87.1% | 93.7% | 107.2% | -58. | -2. |
| CS | 716 | 651 | 29 | 4 | 27 | 5 | 91.6% | 95.6% | 112.8% | -82. | -27. |
| CE | 757 | 603 | 69 | 63 | 16 | 6 | 80.3% | 89.5% | 104.1% | -32. | -19. |

